



General Information

In many industrial sectors and fields of research, temperature measurement is one of the most important parameters which determines product quality, security, and reliability. Temperature sensors are available in several types all of which have a unique performance characteristic. The performance capability of the various sensors are a result of the manufacturing process and component materials associated with their technologies and intended application. It is IST Charter to produce sensors that exceed the industry standard of temperature measurement with additional capability to directly replace older traditional methods and provide the maximum performance. To this end IST has concentrated its development and manufacturing on the process and materials of high-end thin-film temperature sensors. Additionally these processes, partially derived from the semiconductor industry allows IST to manufacture sensors in very small dimensions. Because of their low thermic mass thin-film temperature sensors exhibit a very short response time. IST core technology and processes results in thin-film sensors that combine the good features of traditional wire wound platinum sensors such as accuracy, long-term stability, repeatability, interchangeability and wide temperature range, with the advantages of mass-production, which contributes to their optimal price/performance ratio.

Sensor Construction

The temperature sensor consists of a photo-lithographically structured, high-purity platinum coating arranged in the shape of a meander. The platinum thin-film structures are laser trimmed to form resistive paths with very precisely defined basic value of the resistivity. The sensors are covered with a glass passivation layer; to protect the sensor against mechanical and chemical damage. The bonded leadwires which are additionally covered with a drop of glass make electrical contacts to the resistive structure.

Typical Features

- brief response time
- excellent long-term stability
- low self-heating rate
- excellent price/performance ratio
- small dimensions
- resistant against vibration and temperature shocks
- simple interchangeability

Response Time

The response time $T_{0.63}$ is the time in seconds the sensors need to respond to 63% of the change in temperature. The response time depends on the sensor dimensions, the thermal contact resistance and the enclosure medium.

Long-Term Stability

The change of ohmage after 1,000 hrs at maximum operating temperature until the 7W types amounts to less than 0.03%.

Self Heating

To measure the resistance an electric current has to flow through the element, which will generate heat energy resulting in errors of measurement. To minimize the error, the testing current should be kept low (approximately 1 mA for pt-100). Temperature error $\Delta T = RI^2 / E$; with E = self-heating coefficient in mW/K R = resistance in k Ω , I = measuring current in mA

Measurement current

The amount of thermal transfer from the sensor in application determines how much measuring current can be applied. There is no bottom limit of the measurement current with platinum thin-film. The measurement current depend highly on the application in use. For sensors from 750°C - 1000°C (7W, 8W, 10W) the measurement current must limited at max. 1 mA.

We recommend at:

100 Ω :	typ. 1 mA	max. 5 mA
500 Ω :	typ. 0.5 mA	max. 3 mA
1000 Ω :	typ. 0.3 mA	max. 2 mA
2000 Ω :	typ. 0.2 mA	max. 1 mA
10000 Ω :	typ. 0.1 mA	max. 0.3 mA



SMD 0805 + 1206

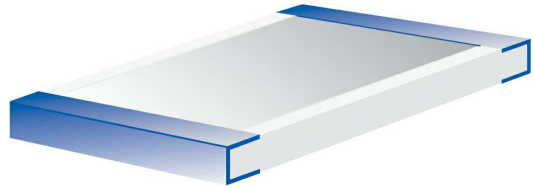
Platinum and Nickel Thin-Film Chip Sensor

Product

To meet the market requirements for increasingly more efficient and economical manufacturing processes, we have developed the SMD 1206 series. A platinum or nickel temperature sensor which is designed for use in markets with a high degree of automation in their production line. This thin-film sensor combines the excellent characteristics of platinum or nickel sensors such as accuracy, long-term stability and reproducibility with the advantages of large-scale production and an optimal price/performance ratio.

Advantages

- Optimised for pick-and-place machines
- Cost-effective assembling
- Easy handling
- Platinum or Nickel thin film elements
- Lead-free (acc. RoHS)



Technical Data

Nominal resistance:	100Ω, 500Ω or 1000Ω		
Temperature range:	-50°C to +150°C (1P, 2P) ; -50°C to +250°C (3P, 4P)		
Temperature coefficient:	Pt: TCR = 3850ppm/K ; Ni: TCR = 6180ppm/K		
Dependence of Resistivity:	DIN 60751 (Platinum) ; former DIN 43760 (Nickel 6180ppm/K) other resistivities on request		
Classes:	Pt: DIN class A ; DIN class B ; 2x DIN class B Ni: DIN, ½ DIN (IST cl. A) DIN 43760: ± 400mK (0°C); ± 7mK/K (>0°C); ± 28mK/K (<0°C)		
Soldering connection:	Contacts: 1P = Contacts tin coated (62Sn/36Pb/2Ag), LMP lead contained 2P = Contacts tin coated (96.5Sn/3Ag/0.5Cu), LMP lead free, RoHS conform 3P = Contacts tin coated (5Sn/93.5Pb/1.5Ag), HMP, RoHS conform 4P* = Contacts gold plated, solderable film *there is no insurance for DIN class A, due to the changed resistance value after soldering. *bondable contacts without bumps available on request.		
Solderability:	235°C ≤ 8s (DIN IEC 68 2-20, Ta Meth 1)		
Resistance to soldering heat:	260°C 10x (DIN IEC 68 2-20, Ta Meth. 1A)		
Long-term stability:	Pt: max. Drift = 0.04% after 1000h at 130°C Ni: max. Drift = 0.1% after 1000 h at 130°C		
Response time:	Water (0.4m/s):	T _{0.63} = 0.25s (1206)	T _{0.63} = 0.2s (0805)
	Air (1m/s):	T _{0.63} = 5.0s (1206)	T _{0.63} = 4.0s (0805)
	The response time refers to the chip, unspoil		
Measuring current:	0.5mA (100Ω) ; 0.4mA (500Ω) ; 0.3mA (1000Ω)		
Self heating:	Water [mW/°C]:	40 (1206, 0805)	
	Air [mW/°C]:	4 (1206, 0805)	
Dimensions:	Pt: 0805 (2.0 x 1.2mm) ; 1206 (3.2 x 1.6mm) Ni: 1206 (3.2 x 1.6mm)		
Other Nominal resistances and tolerances on request.			



INNOVATIVE SENSOR TECHNOLOGY





Nominal values

The nominal or rated value of the sensor is the target value of the sensor resistance at 0° C. The temperature coefficient α is defined

as $\alpha = \frac{R_{100} - R_0}{100 \cdot R_0} [K^{-1}]$ and has the numerical value of 0.00385 K⁻¹ according to DIN IEC 751.

In practice, a value multiplied by 10⁶ is often entered: $TCR = 10^6 \cdot \frac{R_{100} - R_0}{100 \cdot R_0} [ppm/K]$.
In this case, the numerical value is 3850 ppm/K.

Temperatur Characteristic Curve

The characteristic temperature curve determines the dependence of the electrical resistivity on the temperature. The following definition of the temperature curve according to the DIN EN 60751 standard applies:

$$-200 \text{ bis } 0^\circ\text{C} \quad R(t) = R_0 (1 + A \cdot t + B \cdot t^2 + C \cdot [t-100] \cdot t^3)$$

$$0 \text{ bis } 850^\circ\text{C} \quad R(t) = R_0 (1 + A \cdot t + B \cdot t^2)$$

Platinum (3850 ppm/K):

$$A = 3.9083 \cdot 10^{-3} [^\circ\text{C}^{-1}]; B = -5.775 \cdot 10^{-7} [^\circ\text{C}^{-2}];$$

$$C = -4.183 \cdot 10^{-12} [^\circ\text{C}^{-4}]$$

Platinum (3750 ppm/K):

$$A = 3.8102 \cdot 10^{-3} [^\circ\text{C}^{-1}]; B = -6.01888 \cdot 10^{-7} [^\circ\text{C}^{-2}];$$

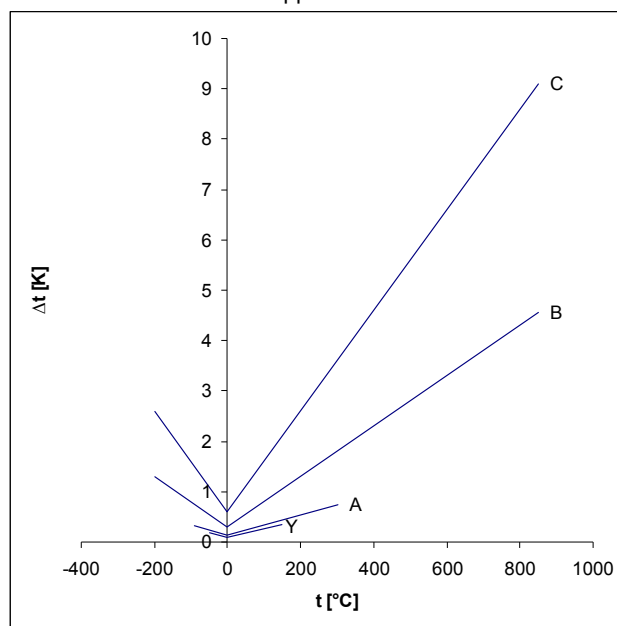
$$C = -6 \cdot 10^{-12} [^\circ\text{C}^{-4}]$$

Platinum (3770 ppm/K):

$$A = 3.92 \cdot 10^{-3} [^\circ\text{C}^{-1}]; B = -6.03 \cdot 10^{-7} [^\circ\text{C}^{-2}];$$

R_0 = Resistance value in ohm at 0°C;

t = temperature in accordance with ITS 90



Tolerance field

Tolerance Classes

temperature sensors are divided into classes according to their limit deviations:

Class	+/- limit deviations in °C (K)	IST AG designation	area of validity of temperature class
DIN 60751, class B	$0.30 + 0.005 \times t $	B	-200°C bis 850°C
DIN 60751, class A	$0.15 + 0.002 \times t $	A	-90°C bis 300°C
1/3 DIN 60751, class B	$0.10 + 0.0017 \times t $	Y	-50°C bis 150°C
2DIN 60751, class B	$0.60 + 0.01 \times t $	C	-200°C bis 850°C
1/5 DIN 60751, class B	$0.06 + 0.001 \times t $	1/5	on request
1/10 DIN 60751, class B	$0.03 + 0.0005 \times t $	1/10	on request

$|t|$ is the numerical value of the temperature in °C without taking into account either negative or positive signs.

Special selection of sensors upon request (e.g. pairings, grouping, special tolerances)



INNOVATIVE SENSOR TECHNOLOGY



Response Times and Self-Heating

Dimension Number	Sensor Size L x W x T / H in mm	Response Time in seconds						Self-Heating			
		Water 0.4 m/s			Air 1m/s			Water $v = 0$ m/s		Air $v = 0$ m/s	
		$T_{0.5}$	$T_{0.63}$	$T_{0.9}$	$T_{0.5}$	$T_{0.63}$	$T_{0.9}$	mW/K	ΔT [mK]*	mW/K	ΔT [mK]*
MiniSens 161	1.6 x 1.2 x 0.25 / 0.9	0.05	0.08	0.18	1	1.2	2.5	12	8.3	1.8	56
SlimSens 308	3.0 x 0.8 x 0.25 / 0.6	0.08	0.10	0.25	1.2	1.5	3.5	15	6.7	2.2	46
232	2.3 x 2.0 x 0.25 / 0.9	0.09	0.12	0.33	2.7	3.6	7.5	40	2.5	4	25
202	2.0 x 2.0 x 0.63 / 1.3	0.12	0.18	0.42	4	5.4	11	36	2.8	3.6	28
216	2.0 x 1.6 x 0.63 / 1.3	0.11	0.16	0.38	3.6	4.9	10.2	32	3.1	3.2	31
232	2.3 x 2.0 x 0.63 / 1.3	0.15	0.2	0.55	4.5	6	12	40	2.5	4	25
325	3.0 x 2.5 x 0.63 / 1.3	0.25	0.3	0.7	5.5	7.5	16	90	1.1	8	13
516	5.0 x 1.6 x 0.63 / 1.3	0.25	0.3	0.7	5.5	7.5	16	80	1.3	7	14
520	5.0 x 2.0 x 0.63 / 1.3	0.25	0.3	0.75	6	8.5	18	80	1.3	7	14
525	5.0 x 2.5 x 0.63 / 1.3	0.33	0.4	0.85	6.5	9	19	90	1.1	8	13
538	5.0 x 3.8 x 0.63 / 1.3	0.35	0.4	0.9	7.5	10	20	140	0.7	10	10
505	5.0 x 5.0 x 0.63 / 1.3	0.4	0.5	1.1	8	11	21	150	0.7	11	9
102	10.0 x 2.0 x 0.63 / 1.3	0.33	0.4	0.85	7.5	10.5	20	140	0.7	10	10
281	1 x 13 x Ø 2.8	2.5	4.5	8	10	15	28	60	1.7	5.5	18
281	2 x 13 x Ø 2.8	2	2.5	5.5	10	12	22	45	2.2	4	25
451	1 x 13 x Ø 4.5	8	10	22	12	22	40	85	1.2	8	13
451	2 x 13 x Ø 4.5	5	6	14	16	18	37	60	1.7	6.5	15
SMD 1206	3.2 x 1.6 x 0.4	0.15	0.25	0.45	3.5	4.2	10	55	1.8	7	14
SMD 0805	2.0 x 1.2 x 0.4	0.10	0.12	0.33	2.5	3	8	38	2.6	4	25
FC 0603	1.5 x 0.75 x 0.4	0.08	0.10	0.25	1.8	2.2	5.5	25	4	2.5	40

*self heating ΔT [mK] measured for Pt100 at 1mA measurement current at 0°C

L: Chip length (sensor length without connections)
W: Sensor width

T: Chip thickness (sensor thickness without connections)
H: Sensor height (incl. connections and strain relief)

Notification: The values in the table are of informative nature only. Due to different measurement conditions you might assess deviant self heating and response time values of your application.

Tolerances of dimensions

Sensor width (W) ± 0.2 mm	Wire length ± 1.0 mm
Sensor length (L) ± 0.2 mm	Tube length ± 0.2 mm
Sensor height (H) ± 0.3 mm	Tube diameter ± 0.1 mm
Sensor thickness (T) ± 0.1 mm	



1P - Product Series

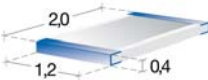
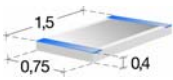
Temperature Range: -60°C... +150°C

Temperature sensors in SMD construction

Soldering depot, RoHS conform (reflow solderable) *only Flip Chip assembly

Technical Data

Temperature range:	-50°C to +150°C (1P, 2P) ; -50°C to +250°C (3P, 4P)
Classes:	Pt: DIN class A; DIN class B; 2x DIN class B
Soldering connection:	Contacts: 1P = Contacts tin coated (62Sn/36Pb/2Ag), LMP lead contained 2P = Contacts tin coated (96.5Sn/3Ag/0.5Cu), LMP lead free, RoHS conform 3P = Contacts tin coated (5Sn/93.5Pb/1.5Ag), HMP, RoHS conform 4P = Contacts gold plated, solderable film - there is no ensurance for DIN class A, due to the changed resistance value after soldering. - bondable contacts without bumps available on request.
Solderability:	235°C ≤ 8s (DIN IEC 68 2-20, Ta Meth 1)
Resistance to soldering heat:	260°C 10x (DIN IEC 68 2-20, Ta Meth. 1A)
Long-term stability:	Pt: max. Drift = 0.04% after 1000h at 130°C

Dimensions in mm	Nominal Resistance at 0°C in Ohm	Chip-Dimensions in mm	Description
	100	LxW 2.0 x 1.2	P0K1.0805.xP.x
	500	LxW 2.0 x 1.2	P0K5.0805.xP.x
	1000	LxW 2.0 x 1.2	P1K0.0805.xP.x
	100	LxW 3.2 x 1.6	P0K1.1206.xP.x
	500	LxW 3.2 x 1.6	P0K5.1206.xP.x
	1000	LxW 3.2 x 1.6	P1K0.1206.xP.x
	100	LxW 1.5 x 0.75	P0K1.0603.xFC.x*
	500	LxW 1.5 x 0.75	P0K5.0603.xFC.x*
	1000	LxW 1.5 x 0.75	P1K0.0603.xFC.x*



Specifications are subject to change without notice

